



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20130117000
Datasheet update for XIO2001
Information Only**

Date: 1/21/2013
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this PCN are for your information only. Please see the attachment details for the planned implementation date.

This notification period is per TI's standard process. Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130117000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
XIO2001PNP	null
XIO2001ZGU	null
XIO2001IZAJ	null
XIO2001IZGU	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130117000	PCN Date:	01/21/2013
Title:	XIO2001 Data Sheet		
Customer Contact:	PCN Manager	Phone:	+1(214) 480-6037
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/> Assembly Materials
<input type="checkbox"/> Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/> Test Process
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process

PCN Details

Description of Change:

The product datasheet(s) is being updated to Remove Note "The input buffer has an internal active pulldown. This pulldown is active at all times" from EXT_ARB_EN and CLKRUN_EN.

The following change history provides further details. These changes may be reviewed at the datasheet links provided



XIO2001

www.ti.com

SCPS212G – MAY 2009 – REVISED DECEMBER 2012

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (May 2012) to Revision G	Page
• Changed External Parts for CLKRUN_EN to include pulldown resistor	20
• Deleted Note from CLKRUN_EN terminal's description	20
• Changed External Parts for EXT_ARB_EN to include pulldown resistor	20
• Deleted Note from EXT_ARB_EN terminal's description	20

The datasheet number will be changing.

Device Family	Change From:	Change To:
XIO2001	SCPS212F	SCPS212G

The updated datasheet(s) can be accessed by the following link(s):

<http://www.ti.com/product/xio2001>

Reason for Change:		
To more accurately reflect device characteristics		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
Electrical specification performance changes as indicated above.		
Changes to product identification resulting from this PCN:		
None		
Product Affected:		
XIO2001IPNP	XIO2001IZGU	XIO2001ZAJ
XIO2001IZAJ	XIO2001PNP	XIO2001ZGU

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com